

ABSTRACT

MULTILAYER SUBSTRATE FOR A BUILDUP WITH A VIA, AND  
METHOD FOR PRODUCING THE SAME

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A multilayer substrate for a buildup with a via,  
which multilayer substrate comprises a base material  
comprising an insulation resin layer on which a  
predetermined hole is formed,

10        wherein an electrodeposition layer is formed by  
circular oscillation electroplating on the inside wall  
surface of the hole and on the predetermined surface of  
the insulation resin layer,

15        the electrodeposition layer on the inside wall  
surface of the hole being formed in a thickness greater  
than the electrodeposition layer formed on the surface of  
the insulation resin layer and a method for the production  
of the substrate.

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